

Load Share Controller

FEATURES

- 2.7V to 20V Operation
- 8-Pin Package
- Requires Minimum Number of External Components
- Compatible with Existing Power Supply Designs Incorporating Remote Output Voltage Sensing
- Differential Share Bus
- Precision Current Sense Amplifier with Gain of 40
- UVLO (Undervoltage Lockout) Circuitry
- User Programmable Share Loop Compensation

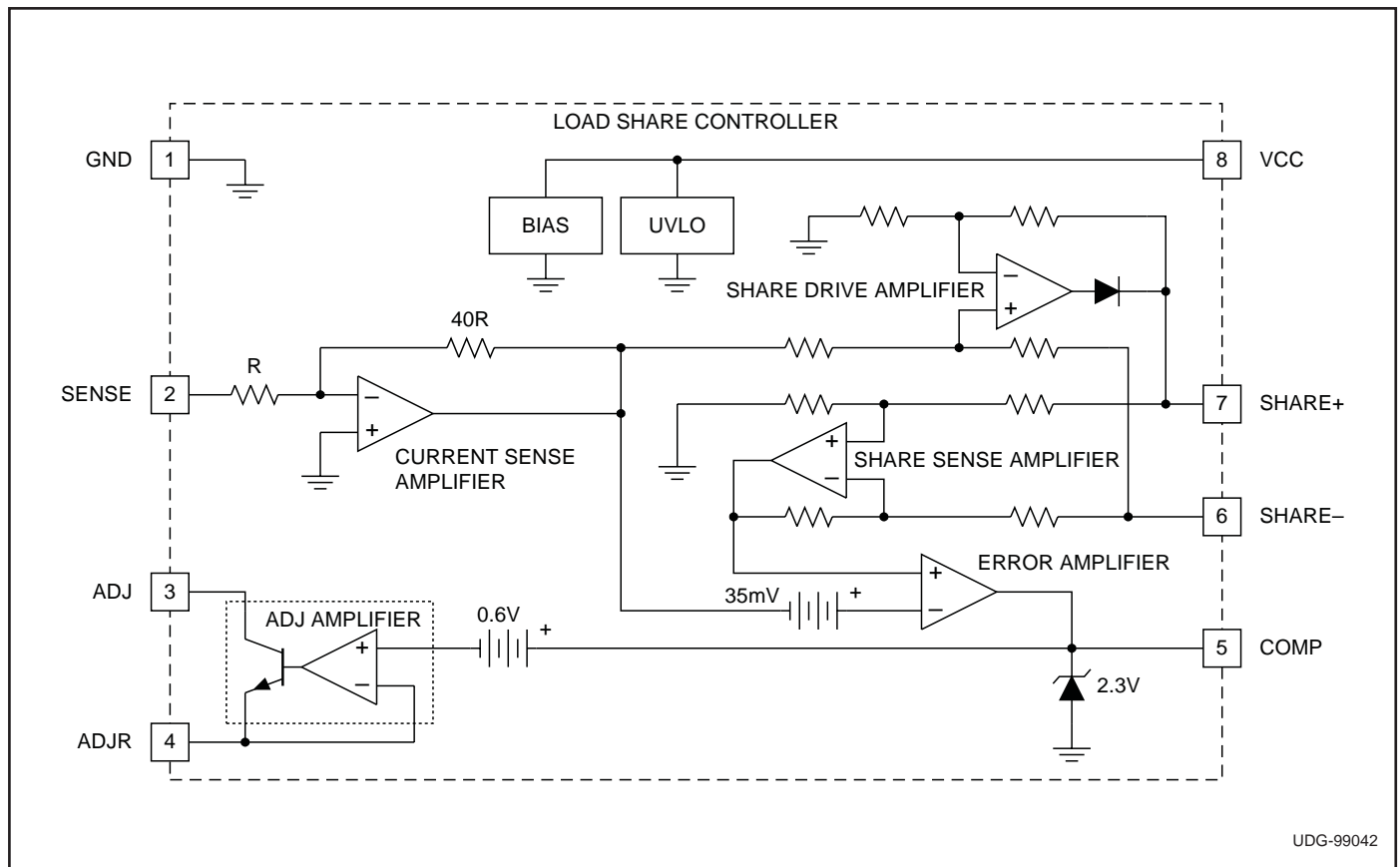
DESCRIPTION

The UC3902 load share controller is an 8-pin device that balances the current drawn from independent, paralleled power supplies. Load sharing is accomplished by adjusting each supply's output current to a level proportional to the voltage on a share bus.

The master power supply, which is automatically designated as the supply that regulates to the highest voltage, drives the share bus with a voltage proportional to its output current. The UC3902 trims the output voltage of the other paralleled supplies so that they each support their share of the load current. Typically, each supply is designed for the same current level although that is not necessary for use with the UC3902. By appropriately scaling the current sense resistor, supplies with different output current capability can be paralleled with each supply providing the same percentage of their output current capability for a particular load.

A differential line is used for the share bus to maximize noise immunity and accommodate different voltage drops in each power converter's ground return line. Trimming of each converter's output voltage is accomplished by injecting a small current into the output voltage sense line, which requires a small resistance (typically $20\Omega - 100\Omega$) to be inserted.

BLOCK DIAGRAM



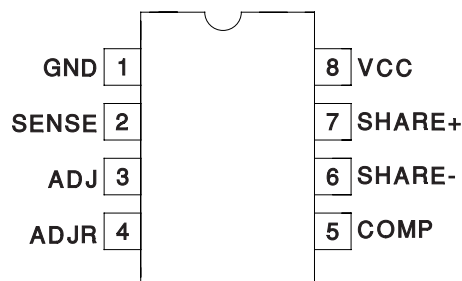
ABSOLUTE MAXIMUM RATINGS

Supply Voltage (ADJ and VCC)	−0.3V to 20V
SENSE Voltage	−5V to +5V
ADJR, COMP Voltage	−0.3V to +4V
SHARE−, SHARE+ Voltages	−0.3V to 10V
SHARE+ Current	−100mA to +10mA
ADJ Current	−1mA to +30mA
Storage Temperature	−65°C to +150°C
Junction Temperature	−55°C to +150°C
Lead Temperature (Soldering, 10sec.)	+300°C

All voltages are with respect to pin 1. Currents are positive into, negative out of the specified terminal. Consult Packaging Section of the Databook for thermal limitations and considerations of packages.

CONNECTION DIAGRAM

DIL-8, SOIC-8 (Top View)
N, J and D Package



ELECTRICAL CHARACTERISTICS: Unless otherwise specified, $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$ for UC1902, -40°C to $+85^\circ\text{C}$ for UC2902, 0°C to 70°C for UC3902, $V_{CC} = 5\text{V}$, $R_{ADJR} = 1\text{k}\Omega$, $V_{ADJ} = 5\text{V}$, $COMP = 5\text{nF}$ capacitor to GND, $V_{SHARE-} = 0\text{V}$, $T_A = T_J$.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Power Supply					
Supply Current	SHARE+ = 1V, SENSE = 0V		4	6	mA
	VCC = 20V		6	10	mA
Undervoltage Lockout					
Startup Voltage	SHARE+ = 0.2V, SENSE = 0V, COMP = 1V	2.3	2.5	2.7	V
Hysteresis	SHARE+ = 0.2V, SENSE = 0V, COMP = 1V	60	100	140	mV
Current Sense Amplifier					
Input Offset Voltage	$0.1\text{V} \leq \text{SHARE+} \leq 1.1\text{V}$	−2.5	−0.5	1.5	mV
Gain SENSE to SHARE	$0.1\text{V} \leq \text{SHARE+} \leq 1.1\text{V}$	−41	−40	−39	V/V
Input Resistance		0.6	1	1.5	k Ω
Share Drive Amplifier					
SHARE+ High	VCC = 2.5V, SENSE = −50mV, ISHARE+ = −1mA	1.2	1.4		V
	VCC = 12V, SENSE = −250mV, ISHARE+ = −1mA	9.6	10	10.4	V
	VCC = 20V, SENSE = −250mV, ISHARE+ = −1mA	9.6	10	10.4	V
SHARE+ Low	VCC = 2.5V, SENSE = +10mV, ISHARE+ = −1mA		20	50	mV
	VCC = 12V, SENSE = +10mV, ISHARE+ = −1mA		20	50	mV
	VCC = 20V, SENSE = +10mV, ISHARE+ = −1mA		20	50	mV
SHARE+ Output Voltage	Measures SHARE+, SENSE = 0mV, RSHARE+ = 200 Ω resistor SHARE+ to GND		20	40	mV
CMRR	$0 \leq \text{SHARE-} \leq 1\text{V}$, SENSE used as input to amplifier	50	90		dB
Load Regulation	Load on SHARE+, $-1\text{mA} \leq I_{\text{LOAD}} \leq -20\text{mA}$, SENSE = −25mV		0	20	mV
Short Circuit Current	SHARE+ = 0V, SENSE = −25mV	−85	−50	−20	mA
Slew Rate	SENSE = +10mV to −90mV Step, 200 Ω resistor SHARE+ to GND	0.16	0.27	0.37	V/ μs
	SENSE = −90mV to +10mV Step, 200 Ω resistor SHARE+ to GND	0.12	0.24	0.34	V/ μs

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PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Share Sense Amplifier					
Input Impedance	SHARE+ = 1V, SHARE- = 1V, SENSE = +10mV	10	15		k Ω
	200 Ω resistor SHARE+ to GND, SHARE- = 1V, SENSE = +10mV	15	17		k Ω
Threshold	SENSE = 0V	41	70	100	mV
CMRR SHARE	$0 \leq \text{SHARE-} \leq 1\text{V}$, SENSE = -2.5mV	50	60		dB
AVOL from SHARE+ to ADJR	SENSE = -2.5mV, 5nF capacitor COMP to GND, 1k resistor ADJR to GND	50	68		dB
	SENSE = -2.5mV, 5nF capacitor COMP to GND, 150 Ω resistor ADJR to GND	50	66		dB
Slew Rate	SHARE+ = Step of 0mV to 300mV through a 200 Ω resistor, $R_{\text{COMP}} = 500\Omega$ resistor to 1.5V, SENSE = 10mV	0.4	0.7	1	V/ μs
Error Amplifier Section					
Transconductance, SHARE+ to COMP	200 Ω resistor SHARE+ to GND	3.2	4.5	5.5	mS
IOH	COMP = 1.5V, SHARE+ $\geq +300\text{mV}$, SENSE = +10mV	-400	-325	-230	μA
IOL	200 Ω resistor SHARE+ to GND, COMP = 1.5V, SENSE = +10mV	100	150	200	μA
Input Offset Voltage		15	35	65	mV
$\Delta \text{VIO}/\Delta \text{VSENSE}$	1k Resistor, ADJR to GND, $-2.5\text{mV} < \text{SENSE} < -25\text{mV}$	-6	0	6	mV/V
ADJ Amplifier					
ADJR Low Voltage	SENSE = +10mV, 200 Ω resistor SHARE+ to GND	-1	0	1	mV
ADJR High Voltage	SENSE = +10mV, SHARE+ = 1V	1.4	1.8	2.1	V
Current Gain ADJR to ADJ	ADJR Current = -0.5mA, ADJ = 2.5V, SENSE = +10mV, SHARE+ = 1V	0.96	0.99	1	A/A
	ADJR Current = -0.5mA, ADJ = 20V, SENSE = +10mV, SHARE+ = 1V	0.96	0.99	1	A/A
	ADJR Current = -10mA, ADJ = 2.5V, SENSE = +10mV, SHARE+ = 1V	0.96	0.99	1	A/A
	ADJR Current = -10mA, ADJ = 20V, SENSE = +10mV, SHARE+ = 1V	0.96	0.99	1	A/A

PIN DESCRIPTIONS

ADJ: Current output of adjust amplifier circuit (NPN collector).

ADJR: Current adjust amplifier range set (NPN emitter).

COMP: Output of error amplifier, input of adjust amplifier. This is where the compensation capacitor is connected.

GND: Local power supply return and signal ground.

SENSE: Inverting input of current sense amplifier.

SHARE+: Positive input from share bus or drive to share bus.

SHARE-: Reference for SHARE+.

VCC: Local power supply (positive).



APPLICATION INFORMATION (cont.)

The values of five passive components must be determined to configure the UC3902 load share controller. The output and return lines of each converter are connected together at the load, with current sense resistor R_{SENSE} inserted in each negative return line. Another resistor, R_{ADJ} , is also inserted in each positive remote sense line. The differential share bus terminals (SHARE+ and SHARE-) of each UC3902 are connected together respectively, and the SHARE- node is also connected to the system ground. A typical application is illustrated in Figure 1.

The load share controller design can be executed by following the next few steps:

Step 1.

$$R_{SENSE} = \frac{V_{SHARE}(\max)}{A_{CSA} \cdot I_O(\max)}$$

where A_{CSA} is 40, the gain of the current sense amplifier.

At full load, the voltage drop across the R_{SENSE} resistor is $I_O(\max) \cdot R_{SENSE}$. Taking into account the gain of the current sense amplifier, the voltage at full load on the current share bus,

$$V_{SHARE}(\max) = A_{CSA} \cdot I_O(\max) \cdot R_{SENSE}.$$

This voltage must stay 1.5V below V_{CC} or below 10V whichever is smaller. V_{SHARE} represents an upper limit but the designer should select the full scale share bus voltage keeping in mind that every volt on the load share bus will increase the master controller's supply current by approximately 100mA times the number of slave units connected parallel.

Step 2.

$$R_G = \frac{V_{ADJ}(\max)}{I_{ADJ}(\max)}$$

Care must be taken to ensure that $I_{ADJ}(\max)$ is low enough to ensure that both the drive current and power dissipation are within the UC3902's capability. For most applications, an $I_{ADJ}(\max)$ current between 5mA and 10mA is acceptable. In a typical application, a 360Ω R_G resistor from the ADJR pin to ground sets $I_{ADJ}(\max)$ to approximately 5mA.

Step 3.

$$R_{ADJ} = \frac{\Delta V_O(\max) - I_O(\max) \cdot R_{SENSE}}{I_{ADJ}(\max)}$$

R_{ADJ} must be low enough to not affect the normal operation of the converter's voltage feedback loop. Typical R_{ADJ} values are in the 20Ω to 100Ω range depending on V_O , $\Delta V_O(\max)$ and the selected $I_{ADJ}(\max)$ value.

Step 4.

$$C_C = \frac{G_M}{2 \cdot \pi \cdot f_C} \cdot \frac{R_{ADJ}}{R_G} \cdot \frac{R_{SENSE}}{R_{LOAD}} \cdot A_{CSA} \cdot A_{PWR}(f_C)$$

The share loop compensation capacitor, C_C is calculated to produce the desired share loop unity gain crossover frequency, f_C . The share loop error amplifier's transconductance, G_M is nominally 4.5ms. The values of the resistors are already known. Typically, f_C will be set at least an order of magnitude below the converter's closed loop bandwidth. The load share circuit is primarily intended to compensate for each converter's initial output voltage tolerance and temperature drift, not differences in their transient response. The term $A_{PWR}(f_C)$ is the gain of the power supply measured at the desired share loop crossover frequency, f_C . This gain can be measured by injecting the measurement signal between the positive output and the positive sense terminal of the power supply.

Step 5.

$$R_C = \frac{1}{2 \cdot \pi \cdot f_C \cdot C_C}$$

A resistor in series with C_C is required to boost the phase margin of the load share loop. The zero is placed at the load share loop crossover frequency, f_C .

When the system is powered up, the converter with the highest output voltage will tend to source the most current and take control of the share bus. The other converters will increase their output voltages until their output currents are proportional to the share bus voltage minus 50mV. The converter which in functioning as the master may change due to warmup drift and differences in load and line transient response of each converter.

ADDITIONAL INFORMATION

Please refer to the following Unitrode topic for additional application information.

[1] Application Note U-163, *The UC3902 Load Share Controller and Its Performance in Distributed Power Systems* by Laszlo Balogh.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UC2902D	ACTIVE	SOIC	D	8		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2902DG4	ACTIVE	SOIC	D	8		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2902DTR	ACTIVE	SOIC	D	8		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2902DTRG4	ACTIVE	SOIC	D	8		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2902N	ACTIVE	PDIP	P	8		Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2902NG4	ACTIVE	PDIP	P	8		Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3902D	ACTIVE	SOIC	D	8		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3902DG4	ACTIVE	SOIC	D	8		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3902DTR	ACTIVE	SOIC	D	8		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3902DTRG4	ACTIVE	SOIC	D	8		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3902N	ACTIVE	PDIP	P	8		Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3902NG4	ACTIVE	PDIP	P	8		Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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